PRODUCT	:	**LCD MODULE**
MODEL NO	:	**YTS210HLAB-01-100N**
SUPPLIER	:	**Yes Optoelectronics Co.,Ltd**
DATE	:	**Jun.20.2018**

SPECIFICATION

Prepared by	Checked	Approved
LIANGYUEYAO	**LIJING**	**XIAOYU**

CUSTOMER:
MODEL NO.: DATE:

Approved	Checked	Department

ADD: No.288Yueling Road Anshan, Liaoning, CHINA
TEL: 86-412-5211859 FAX: 86-412-5211729 P.C.:114045
E-mail : yes@yes-lcd.com, yeslcd@globalsources.com
Web: http://www.yes-lcd.com
http://www.asiansources.com/sante.com

CONTENTS

Revision Record

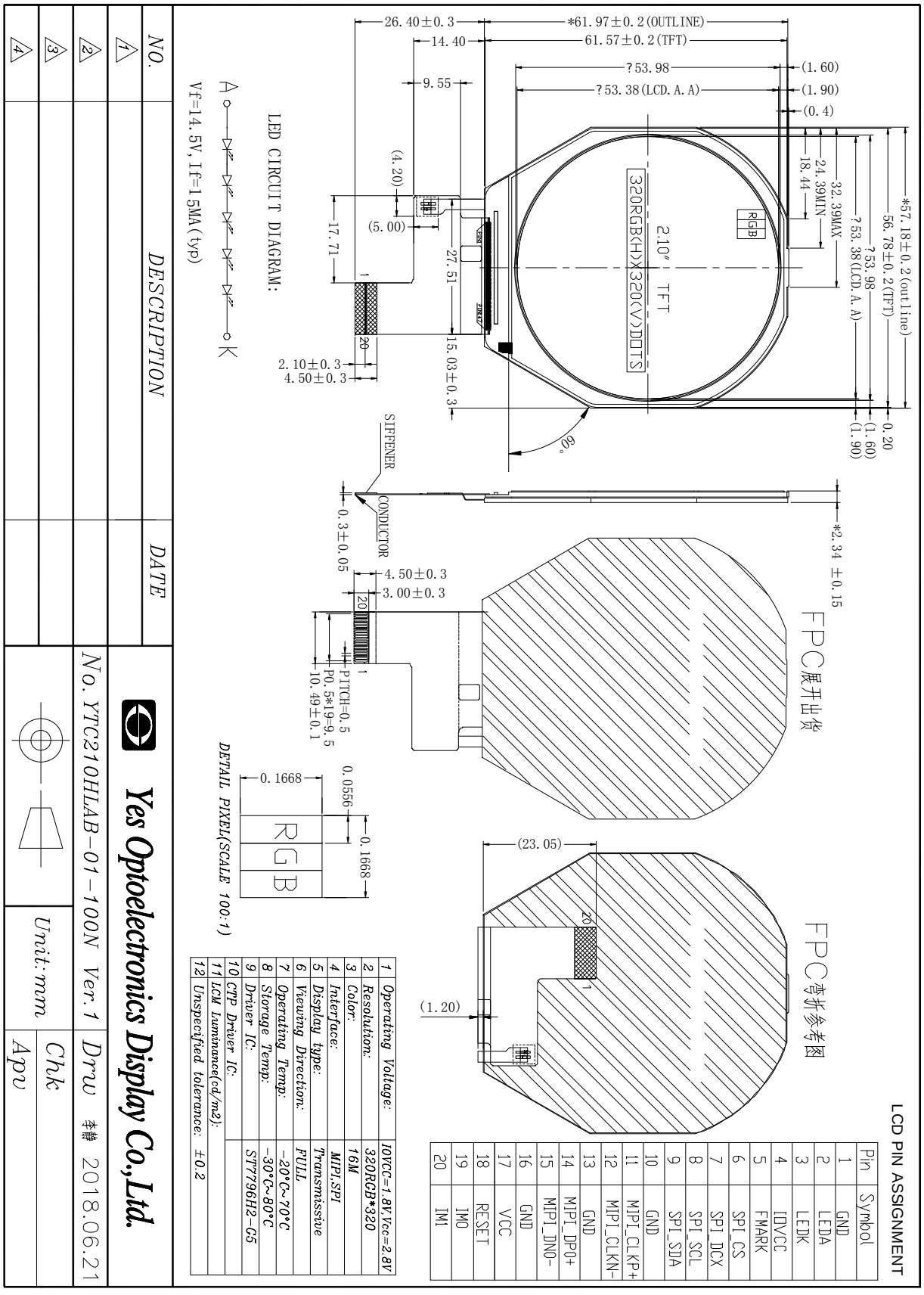
Rev No.	Rev Date	Contents	Remarks
1.0	2018.06.20	New creation	

1. General Specifications

No	Item	Contents	Unit
1	Size	2.1	inch
2	Resolution	320RGB*320	
3	Interface	SPI /MIPI	
4	Color Depth	16	M
6	Pixel Pitch	0.1668*0.1668	mm
7	Pixel Arrangement	RGB Vertical Stripe	
8	Display Mode	Transmissive,IPS,NB	
10	Viewing Direction	Full view	o'clock
11	LCM (W x H x D)	57.18*61.97*2.34	mm
12	Active Area (W x H)	53.38*53.38	mm
13	With/Without TSP	Without TSP	
14	LED Numbers	4	

2. Mechanical Drawing

CUSTOMER'S APPROVED:	DATE:	PAGE:



NO.	DESCRIPTION	DATE
1		
2		
3		
4		

1	Operating Voltage:
2	Resolution:
3	Color:
4	Interface:
5	Display type:
6	Viewing Direction:
7	Operating Temp:
8	Storage Temp:
9	Driver IC:
10	CTP Driver IC:
11	LCM Luminance(cd/m2):
12	Unspecified tolerance:

IOVCC=1.8V,Vcc=2.8V
320RGB*320
16M
MIPI,SPI
Transmissive
FULL
-20°C~70°C
-30°C~80°C
ST7796H2-G5
±0.2

LCD PIN ASSIGNMENT

Pin	Symbol
1	GND
2	LEDA
3	LEDK
4	IOVCC
5	FMARK
6	SPI_CS
7	SPI_DCX
8	SPI_SCL
9	SPI_SDA
10	GND
11	MIPI_CLKP+
12	MIPI_CLKN-
13	GND
14	MIPI_DP0+
15	MIPI_DN0-
16	GND
17	VCC
18	RESET
19	IM0
20	IM1

Yes Optoelectronics Display Co,Ltd.

No. YTC210HLAB-01-100N Ver.1 | Drw 李静 2018.06.21 | Chk | Apv | Unit:mm

3. PIN Assignment

Interface NO. 接口序号	Symbol 符号	I/O or connect to 输入/出或连接到	Description 描述	When not in use 不用时
1	GND	Power	POWER GROUND	/
2	LEDA	LED driver	LED light Anode	OPEN
3	LEDK	LED driver	LED light Cathode	OPEN
4	IOVCC	Power	Power supply for I/O system.	/
5	FMARK	Out	Tearing effect output	OPEN
6	SPI_CS	In	Chip selection pin.	GND/IOVCC
7	SPI_DCX	In	Display data/command selection pin in SPI interface	GND/IOVCC
8	SPI_SCL	In	Serial input clock	GND/IOVCC
9	SPI_SDA	In/Out	SPI interface input/output pin	GND/IOVCC
10	GND	Power	POWER GROUND	/
11	MIPI_CLKP+	In	Positive polarity of low voltage differential clock signal	OPEN
12	MIPI_CLKN-	In	Negative polarity of low voltage differential clock signal	OPEN
13	GND	Power	POWER GROUND	/
14	MIPI_DP0+	In/Out	Positive polarity of low voltage differential data signal	OPEN
15	MIPI_DN0-	In/Out	Negative polarity of low voltage differential data signal	OPEN
16	GND	Power	POWER GROUND	/
17	VCC	Power	Power supply for analog and booster circuits	OPEN
18	RESET	In	Reset the device	/
19	IM0	In	The interface mode select.	/
20	IM1	In	The interface mode select.	/

-The SPI or MIPI interface mode select.

IM1	IM0	MPU Interface Mode	Data pin
0	0	Reserve	-
0	1	3SPI	SPI_SDA
1	0	MIPI	DN0-/DP0+,CLKN-/CLKP+
1	1	4 Line SPI	SPI_SDA

4. Absolute Maximum Rating

AGND = GND = 0V , Ta = 25° C

Parameter of absolute maximum ratings 参数	Symbol 符号	Min 最小值	Max 最大值	Unit 单位
Supply voltage for logic 逻辑电压	VCC/IOVCC	-0.3	4.6	V
Input voltage 输入电压	VIN	-0.5	IOVCC+0.5	V
Operating temperature 操作温度	Top	-20	70	°C
Storage temperature 储存温度	TST	-30	80	°C
Humidity 湿度	RH	-	90%(Max60 °C)	RH

Note: Absolute maximum ratings means the product can withstand short-term, NOT more than 120 hours. If the product is a long time to withstand these conditions, the life time would be shorter.
备注:极限条件仅指产品能短暂承受的范围, 不可超过 120 小时。如果产品长时间在极限条件, 将有损产品的使用寿命。

5. Electrical Characteristics

5.1. Recommended Operating Condition

AGND = GND = 0V , Ta = 25° C

Parameter of DC characteristics 参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Supply voltage for logic 逻辑电压	VCC	2.6	2.8	3.3	V
I/O power supply 接口电压	IOVCC	1.7	1.8	3.3	V
Input Current 输入电流	Idd	-	TBD	TBD	mA
Input voltage 'H' level 输入高电平	VIH	0.7IOVCC	-	IOVCC	V
Input voltage 'L' level 输入低电平	VIL	GND	-	0.3IOVCC	V
Output voltage 'H' level 输出高电平	VOH	0.8IOVCC	-	-	V
Output voltage 'L' level 输出低电平	VOL	GND	-	0.2IOVCC	V

5. 2.Rcommended Driving Condition for Backlight

Ta = 25° C

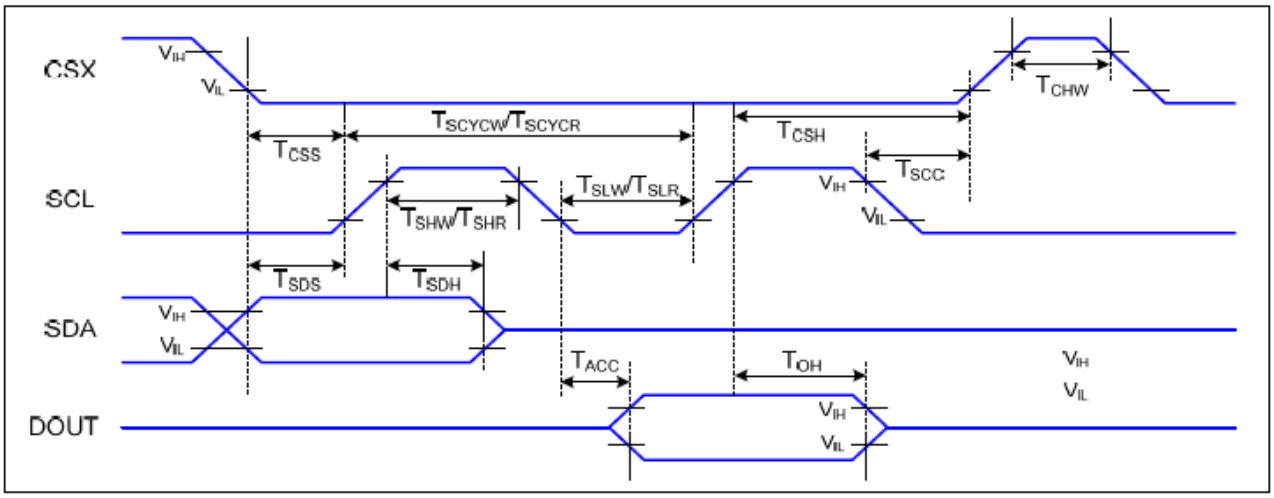
Item of backlight characteristics 项目	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage正向电压	Vf	12.5	14.5	16.5	V	If=15mA;Ta=25℃
Number of LED 灯数	-	-	5	-	Piece	-
Connection mode 连接类型	P/S	-	Serial	-	-	-

Using condition: constant current driving method If=15mA(+/-10%).

6. Timing Characteristics

6.1. AC Electrical Characteristics

3-SPI Serial Data Transfer Interface Characteristics:



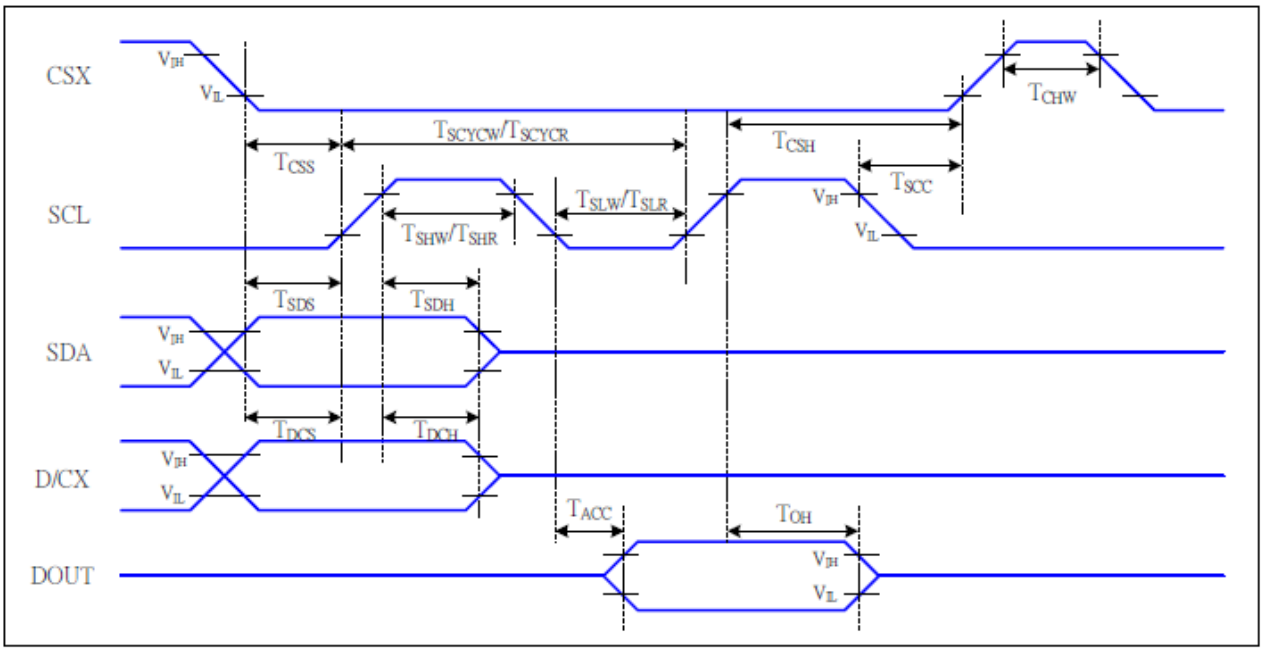
3-SPI Interface Timing Characteristics

VDDI=1.8V,VDDA=2.8V, AGND=DGND=0V, Ta=25 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	15		ns	
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

3-SPI Interface Characteristics

4-SPI Serial Data Transfer Interface Characteristics:



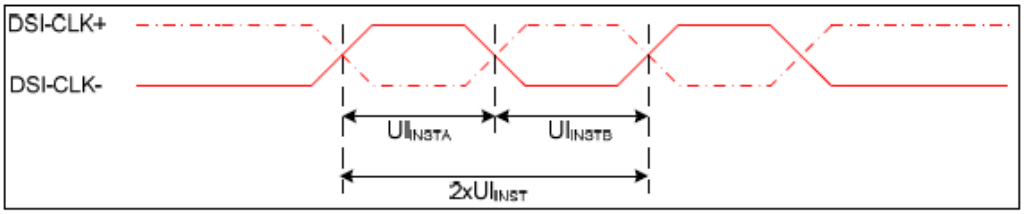
4-SPI Interface Timing Characteristics

VDDI=1.8V,VDDA=2.8V, AGND=DGND=0V, Ta=25 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	15		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

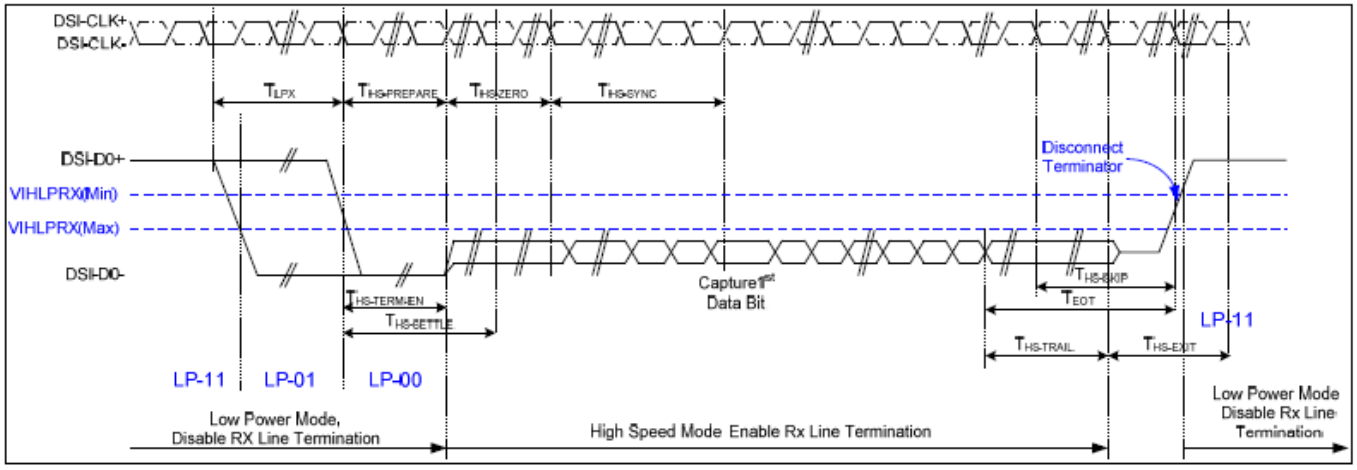
MIPI Interface Characteristics

High Speed Mode – Clock Channel Timing



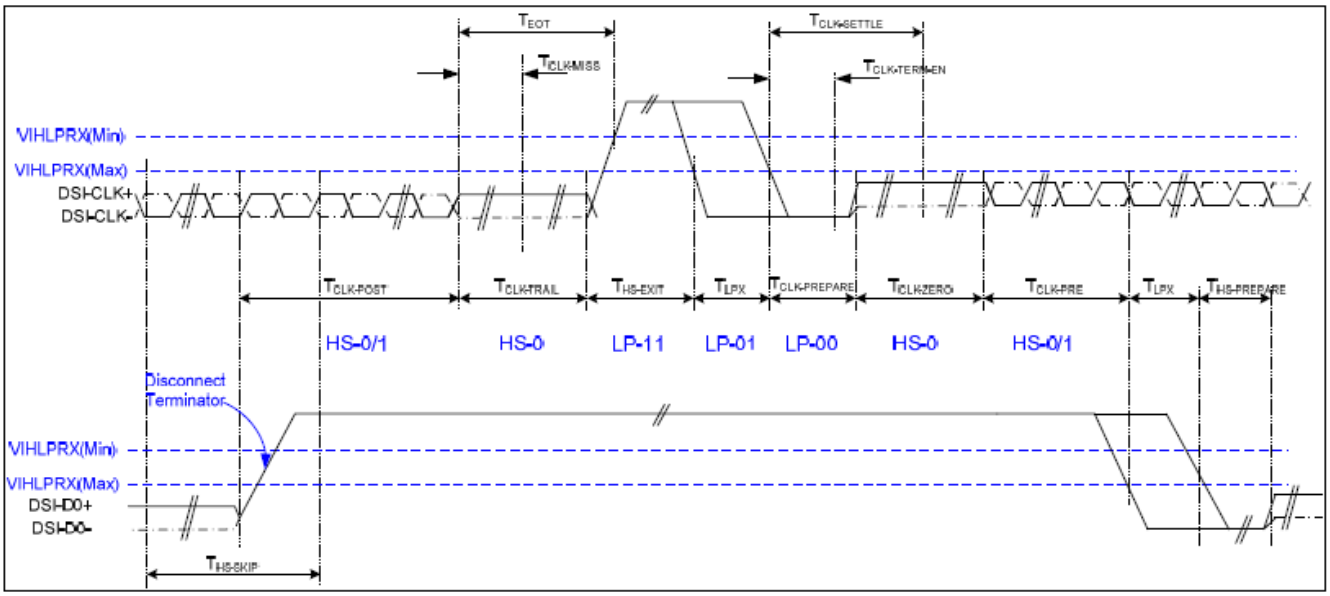
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-DATA_P/N	2xUI INST	Double UI instantaneous	4	25	ns	
DSI-DATA_P/N	UI INSTA ,UI INSTB	UI instantaneous Half	2	12.5	ns	

High-Speed Data Transmission



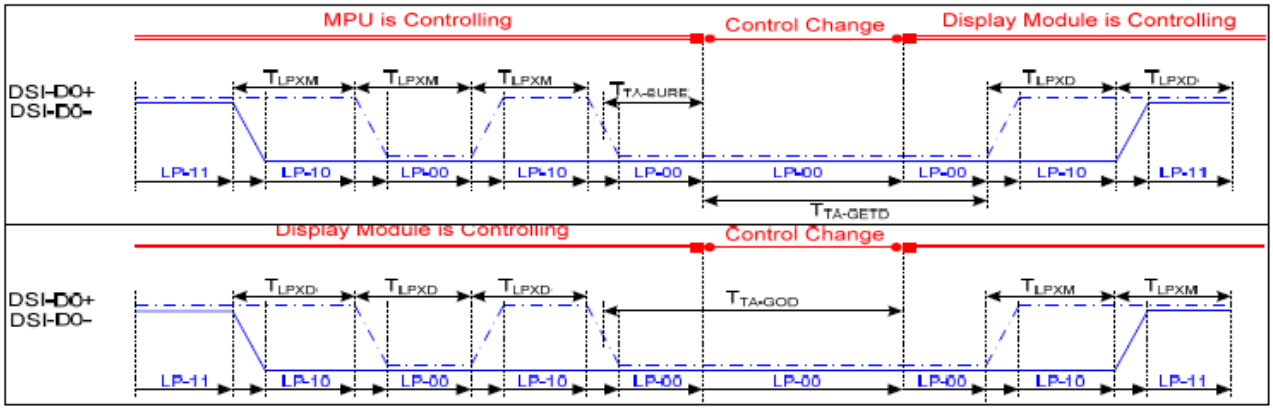
Parameter	Symbol	MIN	TYP	MAX	Unit
Time to drive LP-00 to prepare for HS transmission	$T_{HS-PREPARE}$	40+4UI		85+6UI	ns
Time from start of t HS-TRAIL or t CLK-TRAIL period to start of LP-11 state	T_{EOT}			105+12UI	ns
Time to enable data receiver line termination measured from when Dn crosses VILMAX	$T_{HS-TERM-EN}$			35+4UI	ns
Time to drive flipped differential state after last payload data bit of a HS transmission	$T_{HS-TRAIL}$	60+4UI			ns
Time-out at RX to ignore transition period of EoT	$T_{HS-SKIP}$	40		55+4UI	ns
Time to drive LP-11 after HS burst	$T_{HS-EXIT}$	100			ns
Length of any Low-Power state period	T_{LPX}	50			ns
Sync sequence period	$T_{HS-SYNC}$		8UI		ns
Minimum lead HS-0 drive period before the Sync sequence	$T_{HS-ZERO}$	105+6UI			ns

Switching the Clock Lane between Clock Transmission and Low-Power Mode



Parameter	Symbol	MIN	TYP	MAX	Unit
Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	$T_{CLK-POST}$	60+52UI			ns
Detection time that the clock has stopped toggling	$T_{CLK-MISS}$			60	ns
Time to drive LP-00 to prepare for HS clock transmission	$T_{CLK-PREPARE}$	38		95	ns
Minimum lead HS-0 drive period before starting Clock	$T_{CLK-PREPARE}$ +$T_{CLK-ZERO}$	300			ns
Time to enable Clock Lane receiver line termination measured from when Dn cross VIL,MAX	$T_{HS-TERM-EN}$			38	ns
Minimum time that the HS clock must be set prior to any associated date lane beginning the transmission from LP to HS mode	$T_{CLK-PRE}$	8			UI
Time to drive HS differential state after last payload clock bit of a HS transmission burst	$T_{CLK-TRAIL}$	60			ns

Bus Turnaround Procedure

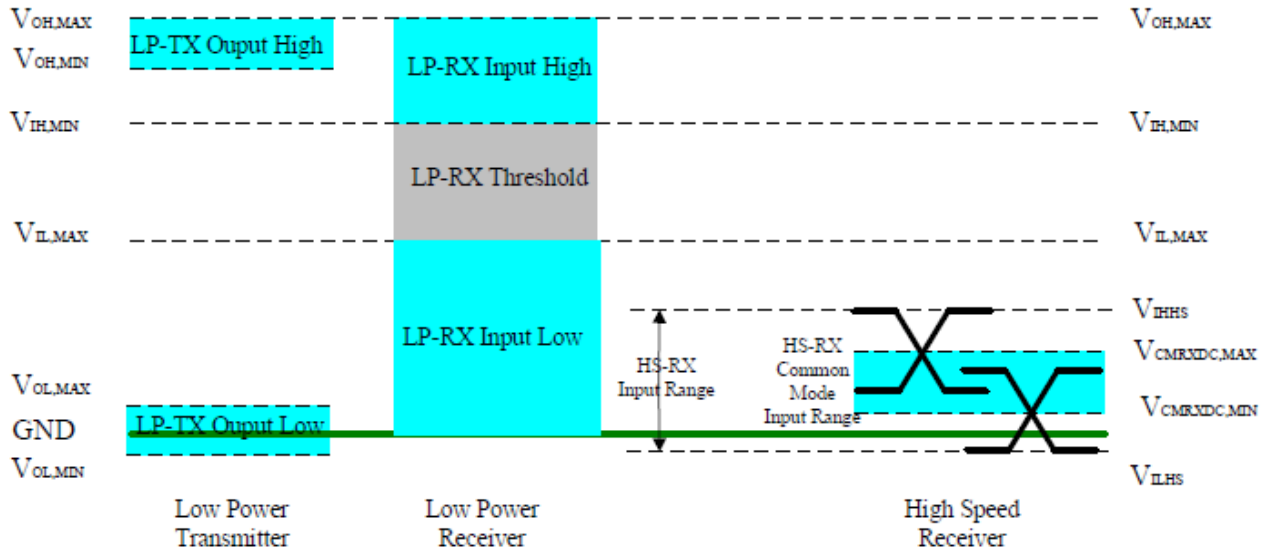


Parameter	Symbol	MIN	TYP	MAX	Unit
Length of any Low-Power state period : Master side	T_{LPX}	50		75	ns
Length of any Low-Power state period : Slave side	T_{LPX}	47.5	50	52.5	ns
Ratio of T_{LPX} (MASTER)/ T_{LPX} (SLAVE) between Master and Slave side	Ratio T_{LPX}	2/3		3/2	
Time-out before new TX side start driving	$T_{TA-SURE}$	T_{LPX}		2 T_{LPX}	ns
Time to drive LP-00 by new TX	T_{TA-GET}		5 T_{LPX}		ns
Time to drive LP-00 after Turnaround Request	T_{TA-GO}		4 T_{LPX}		ns

6.2. DC Electrical Characteristics

DC characteristics for MIPI DSI

- MIPI Signaling Voltage Levels



- MIPI DC characteristics

Parameter	Symbol	Specification			Unit
		MIN	TYP	MAX	
Operation Voltage for MIPI Receiver					
Low power mode operating voltage	V_{LPH}	1.1	1.2	1.3	V
MIPI Characteristics for High Speed Receiver					
Single-ended input low voltage	V_{ILHS}	-40	-	-	mV
Single-ended input high voltage	V_{IHHS}	-	-	460	mV
Common-mode voltage	V_{CMRXDC}	70	-	330	mV
Differential input impedance	Z_{ID}	80	100	125	ohm
MIPI Characteristics for Low Power Mode					
Pad signal voltage range	V_I	-50	-	1350	mV
Logic 0 input threshold	V_{IL}	0	-	550	mV
Logic 1 input threshold	V_{IH}	880	-	1350	mV
Output low level	V_{OL}	-50	-	50	mV
Output high level	V_{OH}	1.1	1.2	1.3	V

6.3. Power on/off sequence

VDDI and VDD can be applied in any order.

VDD and VDDI can be power down in any order.

During power off, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down minimum 120msec after RESX has been released.

During power off, if LCD is in the Sleep In mode, VDDI or VDD can be powered down minimum 0msec after RESX has been released.

CSX can be applied at any timing or can be permanently grounded. RESX has priority over CSX.

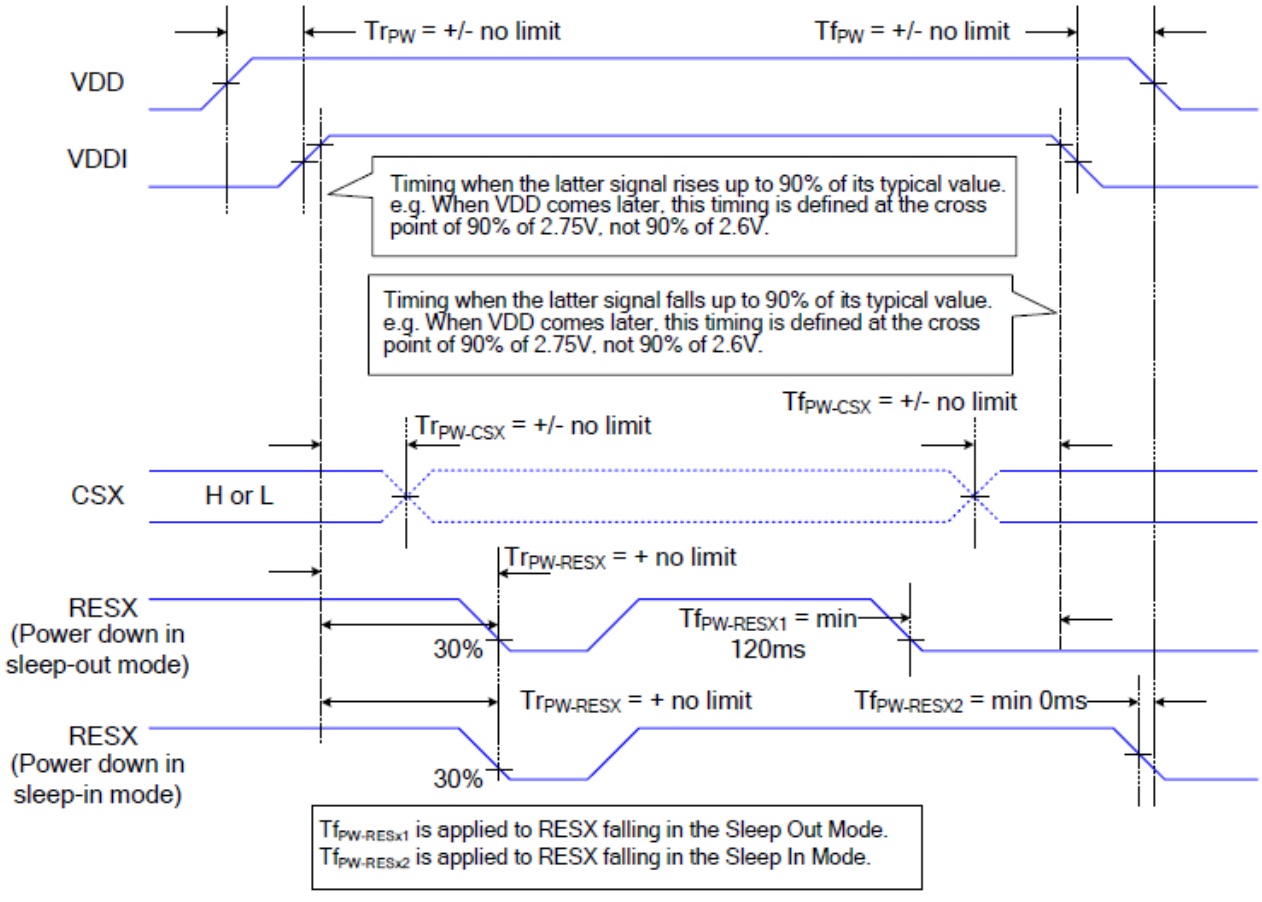
Note 1: There will be no damage to the display module if the power sequences are not met.

Note 2: There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.

Note 3: There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out command. Also between receiving Sleep In command and Power Off Sequence.

Note 4: If RESX line is not held stable by host during Power On Sequence as defined in the sequence below, then it will be necessary to apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is not guaranteed.

The power on/off sequence is illustrated below



7. Optical Characteristics

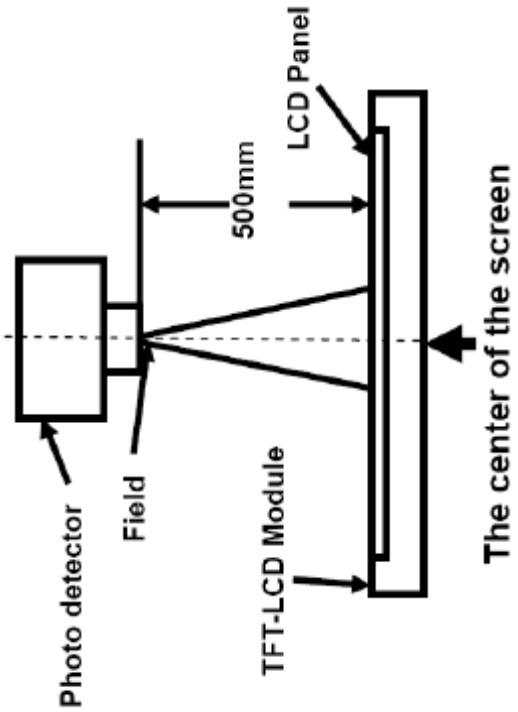
Item		Symbol	Condition	Min	Typ.	Max	Unit	Remark
View Angles		θ T	CR≥10	TBD	TBD		Degree	Note 2
		θ B		TBD	TBD			
		θ L		TBD	TBD			
		θ R		TBD	TBD			
Contrast Ratio		CR	θ = 0°		TBD			Note 1 Note 3
Response Time		T_{ON}	25° C		TBD		ms	Note 1 Note 4
		T_{OFF}						
Chromaticity	W_x	x		TBD	TBD	TBD		Note 1 Note 5
	W_y	y		TBD	TBD	TBD		
Uniformity		U		TBD			%	Note 5
Luminance		L		TBD	TBD		cd/m^2	Note 1 Note 5

Test Conditions:

1. If=15 mA(Backlight current), VCC =2.8 V, the ambient temperature is 25° C.
2. The test systems refer to Note 2.

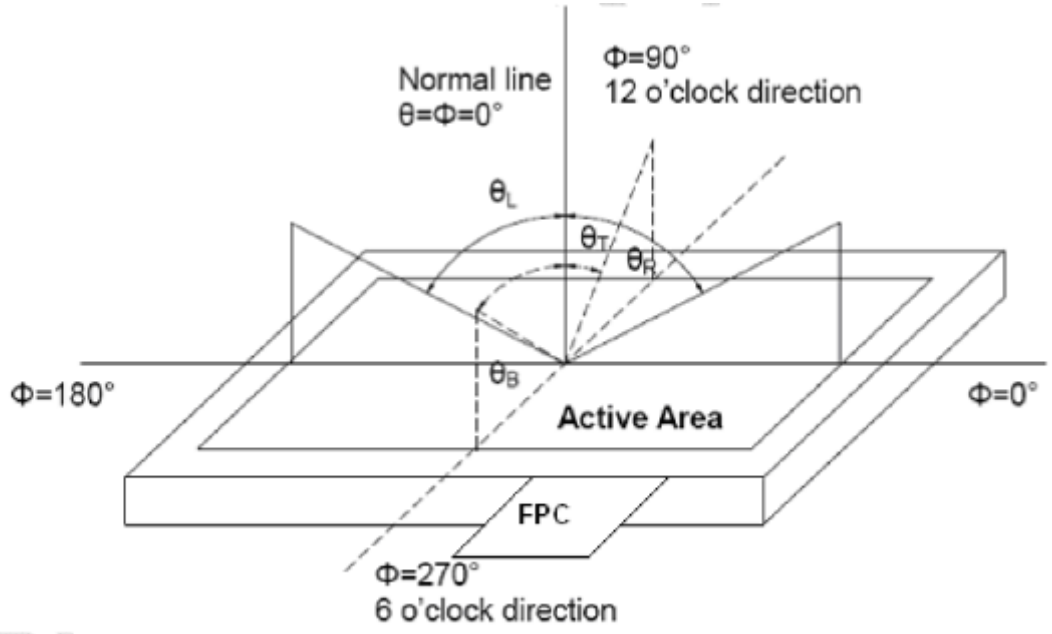
Note1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5Minutes operation, the optical properties are measured at the center point of the LCD screen. ALL input terminals LCD panel must be ground when measuring the center area of the panel.



Item	Photo detector	Field
Contrast Ratio	CS1000	1º
Luminance		
Lum Uniformity		
Chromaticity	CS1000	
Response Time	DMS703	-

Note2: Definition of viewing angle range and measurement system.
Viewing angle is measured at the center point of the LCD by CONOSCOPE (DMS703)

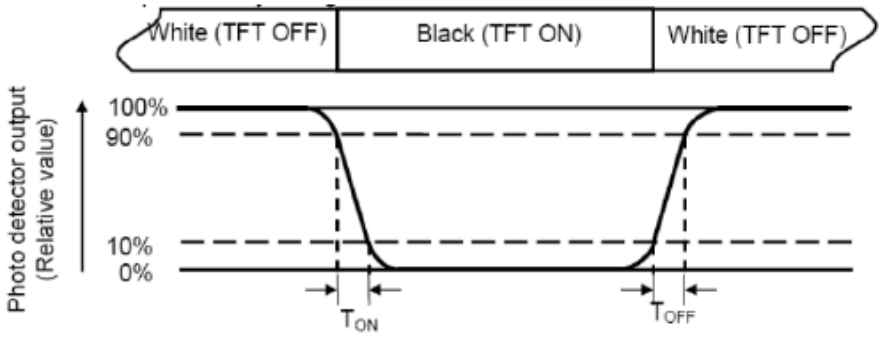


NOTE3: Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD is on the "White" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

“White state ”:The state is that the LCD should drive by Vwhite.

“Black state ”:The state is that the LCD should drive by Vblack.
Vwhite: To be determined Vblack: To be determined
Note4:Definition of Response time
The response time is defined as the LCD optical switching time interval between “White”state and “Black” state. Rise time (T_{ON})is the time between photo detector output intensity changed from 90% to 10%.And fall time (T_{OFF})is the time between photo detector output intensity changed from 10% to90%.

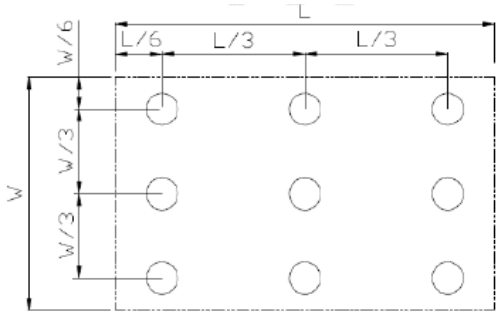


Note5:Definition of color chromaticity（CIE1931）

Color coordinates measured at center point of LCD.
Note6: Definition of Luminance Uniformity
Active area is divided into 9 measuring areas(Refer Fig.2).Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U)=Lmin/Lmax

L--------Active area length W--------Active area width



L max: The measured Maximum luminance of all measurement position.
L min: The measured Minimum luminance of all measurement position.
Note7: Definition of luminance:

Measure the luminance of white state at center point.

8. Environmental/Reliability Test

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80±2℃/240 hours	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Sealleak; 3.Non-display; 4.missing segments; 5.Glass crack; 6.Current Idd is twice higher than initial value.
2	Low Temperature Storage	-30±2℃/240 hours	
3	High Temperature Operating	70±2℃/240 hours	
4	Low Temperature Operating	-20±2℃/240 hours	
5	Temperature Cycle	-30℃~25℃~ 80℃ × 10cycles (30min.) (5min.) (30min.)	
6	Damp Proof Test	40℃±5℃×90%RH/240 hours	
7	Vibration Test	Frequency：10Hz~55Hz~10Hz Amplitude：1.5mm, X，Y，Z direction for total 3hours (Packing condition)	
8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	
9	ESD	Voltage:±8KV R: 330Ω C: 150pF Air discharge, 10time	
		Voltage:±6KV R: 330Ω C: 150pF Contact discharge, 10time	

Remark:
1.The test samples should be applied to only one test item.
2.Sample size for each test item is 5~10pcs.
3.For Damp Proof Test, Pure water(Resistance＞10MΩ) should be used.
4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
6.Please use automatic switch menu(or roll menu) testing mode when test operating mode.

9. Packing Drawing(TBD)

10. Standard Specifications For Product Quality

10.1. Manner of test:

10.1.1 The test must be under 40W fluorescent light, and the distance of view must be at 30±10cm.

10.1.2 Room temperature 25±5℃ Humidity: (60±10)％RH.

10.2. Quality specification

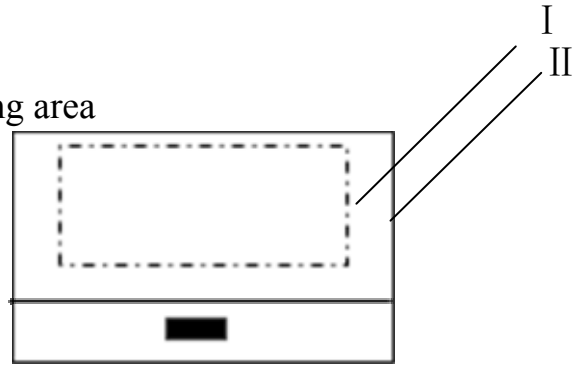
It shall be based on GB2828-87, inspection level Ⅱ .

	IETM	CHECK LEVEL	AQL
MAJOR (MA)	1.Liquid crystal leakage 2.Wrong polarizer 3.Outside dimension 4. Bright dot、Dark dot 5. Display abnormal 6. Class crack	Ⅱ	0.25
MINOR (MI)	1. Spot Defect (Including black spot、white spot、pinhole、foreign particle、bubbles、hurt） 2. fragment 3. Line Defect (Including black line、white line、cratch) 4. Incision defect 5. Newton's ring 6. Other visual defects	Ⅱ	1.0

10.3. Definition of area:

10.3.1 Ⅰ area: viewing area

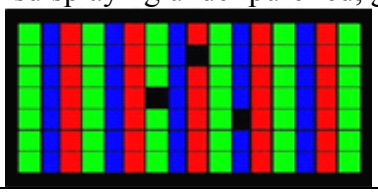
Ⅱ area: outside viewing area



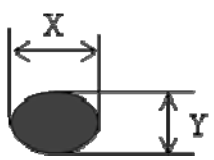
10.4.Standard of appearance test for Ⅰ area: (unit: mm)

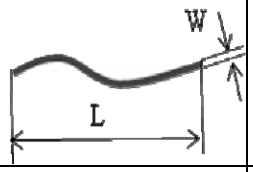
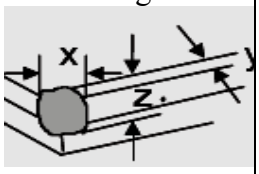
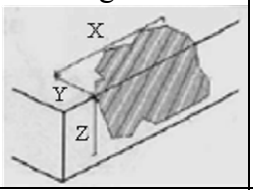
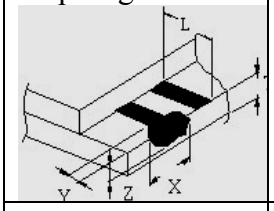
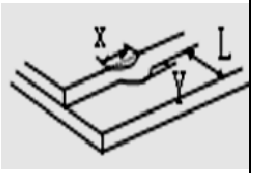
NOTE：Defect ignore for Ⅱ area .

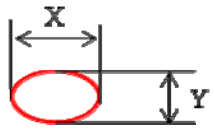
10.4.1 Bright/Dark Dots explain

Name	Explain	Definition
Bright dot	Dots appear bright and unchanged in size in which LCD panel isdisplaying under black pattern 	The definition of dot: The size of a defective dot over 1/2 of single pixel dot is regarded as one defective dot . NOTE: One pixel consists of 3 sub-pixels, including R,G, and B dot.(Sub-pixel = Dot)
Dark dot	Dots appear dark and unchanged in size in which LCD panel isdisplaying under pure red, green, blue pattern. 	
ADJACENT DOT	Adjacent two sub-pixel are defect（define two dot defect）	

10.4.2 Inspection standard

№	Items	Criterion		Checking Manner	Defect Classes
1	Bright/dark dot	Under 6” (contain 6”)	Bright dot：2 Dark dot：N≤4 **Note:** be more than 5mm apart	Checking with eyes	MAJ
		6”-12”	Bright dot：N≤4 Dark dot：N≤5 Total Bright and Dark Dots：N≤8 **Note ：** 1.Two bright dot defects (red, green, blue, and white) should be larger than 15mm； 2.The distance between black dot defects or black and bright dot defects should be more than 5mm apart.		
2	Spot Defect (Including black spot.white spot. Pinhole.foreign particle.bubbles.hurt）  D=(X+Y)/2	Under 6” （contain 6”）	D≤0.1 Ignore 0.1＜D≤0.35 N≤3 0.35＜D N=0	Checking with eyes	MIN
		6”-12”	D≤0.3 Ignore 0.3＜D≤0.6 N≤4 0.6＜D N=0		

№	Items	Criterion		Checking manner	Defect classes
3	Line Defect (Including black Line.white line. scratch) 	Under 6” （contain 6”）	W≤0.02 Ignore 0.02＜W≤0.04 L≤5 N≤2 0.04＜W≤0.06 L≤5 N≤1 W＞0.06 N=0	Checking with eyes	MIN
		6”-12”	W≤0.07 Ignore 0.07＜W≤0.1 L≤10 N≤4 W＞0.1 N=0		
4	Display abnormal	Not allowed		Checking with eyes	MAJ
5	Outside dimension	Accord with drawing		Callipers	MAJ
6	Class crack	Not allowed		Checking with eyes	MAJ
7	Leak	Not allowed		Checking with eyes	MAJ
8	Comer fragment 	X≤3 Y≤3 Z≤T Ignore Note ： 1.No hurt identifying .wire.seal 2.T：Glass thickness X: Length Y: Width Z: thickness		Checking with eyes	MIN
9	Side fragment 	Y≤1 Z≤T Ignore Note ： 1.No hurt identifying .wire.seal 2.T：Glass thickness X: Length Y: Width Z: thickness		Checking with eyes	MIN
	Step fragment 	Y≤1 and Y≤1/4 L		Checking with eyes	MIN
	Incision defect 	Y≤1 and accord with outside dimension		Checking with eyes	MIN

№	Items	Criterion		Checking manner	Defect classes
10	Newton's ring （CTP or Cover board）  D=(X+Y)/2	Under 6" (contain 6")	D≤25 N≤3 D＞25 N=0	Checking with eyes	MIN
		6"-12"	D≤70 N≤5 D＞70 N=0		

11. Precautions for Use of LCD Modules

11.1 Handing Precautions

(1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.

(2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

(3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).

(4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass,tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.

(5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents

- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

(6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

(7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

(8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I O cable
or the backlight cable.

(9) Do not attempt to disassemble or process the LCD module.

(10) NC terminal should be open. Do not connect anything.

(11) If the logic circuit power is off, do not apply the input signals.

(12) Electro-Static Discharge Control,Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary

CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential.Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended.As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

(13)Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

11.2 Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

11.3 Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images

and a slight contrast irregularity may also appear.A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

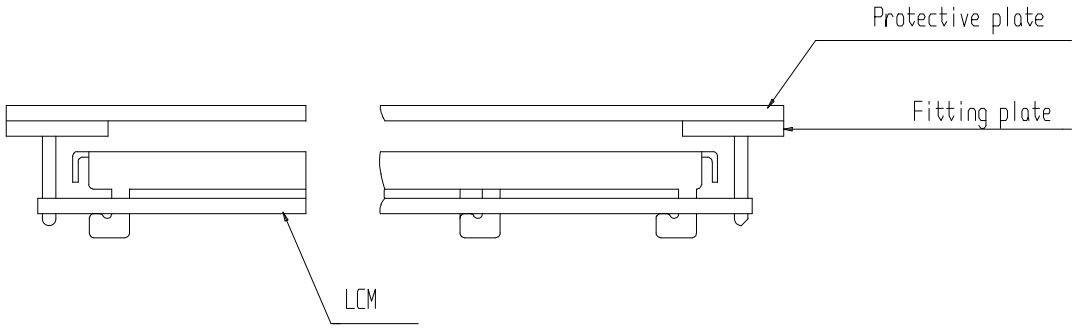
- Exposed area of the printed circuit board.
-Terminal electrode sections.

11.4 USING LCD MODULES

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

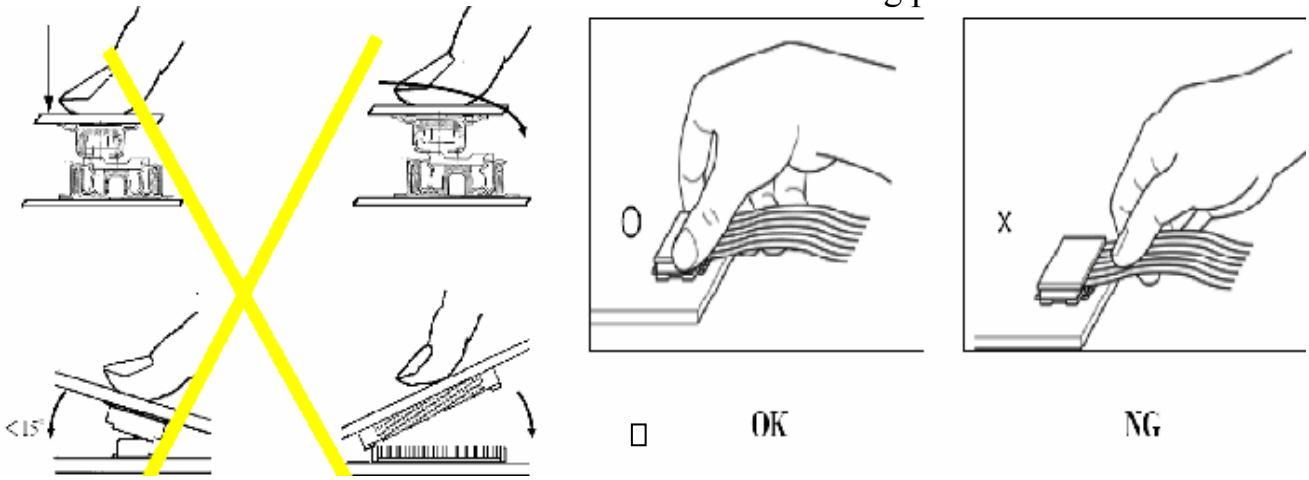
(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ±0.1mm.

Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position,don't assemble or assemble like the method which the following picture shows



Precaution for soldering to the LCM

	Hand soldering	Machine drag	Machine press soldering

No ROHS Product	290°C~350°C. Time : 3-5S.	330°C ~350°C. Speed : 4-8mm/s.	300°C~330C. Time : 3-6S. Press: 0.8~1.2Mpa
ROHS Product	340°C~370°C. Time : 3-5S.	350°C ~370°C. Time : 4-8 mm/s.	330°C~360C. Time : 3-6S. Press: 0.8~1.2Mpa

(1)If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

(2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

(3) When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

(1) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

(2) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.However those phenomena do not mean malfunction or out of order with LCD's, Which will come back in the specified operating temperature.

(3) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

(4) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature,50%RH or less is required.

(5) Input each signal after the positive/negative voltage becomes stable.

(6) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

Safety

(1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

(2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

11.5The disposal of waste

For waste disposal, our recommendations are as follows, please refer to your company

and the relevant provisions of the state laws and regulations of the act accordingly

1. Packing materials disposal for our packaging (carton/PS tray/EPE tray/PET tray)

1)Our company used to recycle and reuse materials, packing materials can be you just need to transfer to material recycling companies

2. Our scrap module can't be recycled for reuse, so please dispose of,

1) Our scrap module can't be recycled for reuse, products and components are "served" can lead to accidents

2) Our scrap can be transfer to material recycling companies, dismantling, to ensure that scrap in relatively advanced technology products, environmental protection measures of relatively perfect environment for processing.

3. WEEE order must be executed in product scrap.

12. Prior Consult Matter

1.①For YES standard products, we keep the right to change material, process ... for improving the product property without notice on our customer.

②For OEM products, if any change needed which may affect the product property, we will consult with our customer in advance.

2.If you have special requirement about reliability condition, please let us know before you start the test on our samples.

13. Factory

FACTORY NAME: YES OPTOELECTRONICS CO.,LTD

FACTORY ADDRESS: No.288Yueling Road Anshan, Liaoning, P.R.CHINA

FACTORY PHONE: 86-412-5211859 FAX: 86-412-5211729